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Layer Stack Legend

	Material	Layer	Thickness	Dielectric Material	Type	Gerber	Dk	Weight	Description
		Top Overlay			Legend	GTO			
1		Surface Material	Top Solder	0.035mm	Solder Resist	Solder Mask	GTS	3,5	
		Nickel, Gold	Top Surface Finish	0.004mm		Surface Finish			
		Copper	L 01	0.043mm	Signal	GTL		0.33oz	Base 12um + GalvCu 35um
		Prepreg		0.110mm	FR-4	Dielectric		4,2	
		Copper	L 02	0.018mm	Signal	G1		0.5oz	
		Core		0.300mm	7628	Dielectric		4,2	
		Copper	L 03	0.018mm	Signal	G2		0.5oz	
		Prepreg		0.180mm	FR-4	Dielectric		4,2	
2		Copper	L 04	0.018mm	Signal	G3		0.5oz	
		Core		0.300mm	7628	Dielectric		4,2	
		Copper	L 05	0.018mm	Signal	G4		0.5oz	
		Prepreg		0.110mm	FR-4	Dielectric		4,2	
		Copper	L 06	0.043mm	Signal	GBL		0.33oz	Base 12um + GalvCu 35um
		Nickel, Gold	Bottom Surface Finish	0.004mm		Surface Finish			
		Surface Material	Bottom Solder	0.035mm	Solder Resist	Solder Mask	GBS	3,5	
			Bottom Overlay		Legend	GBO			
3	Total thickness: 1.236mm								

Transmission Line Structure Table

Impedance Id	Transmission Line	Target Impedance	Calculated Impedance	Trace layer	Narrow Trace Width	Reference layers	Target Tolerance
1	Coated Microstrip	50	49.80	L 01	0.170mm	L 02	10%
2	Offset Stripline	50	50.01	L 03	0.190mm	L 02,L 04	10%
3	Offset Stripline	50	50.01	L 04	0.190mm	L 03,L 05	10%
4	Coated Microstrip	50	49.80	L 06	0.170mm	L 05	10%



Title:TE0890 Layer Stack

A4

Nummer:LS0890
[No Variations]

Rev.02

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Page1 of1

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A

B

C

D